

## Product Change Notification - KSRA-19GIRS482

**Date:** 27 Apr 2017  
**Product Category:** 8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers  
**Notification subject:** CCB 2923 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 200K wafer technology available in 28L QFN package at NSEB assembly site  
**Notification text:** **PCN Status:**  
 Initial notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 200K wafer technology available in 28L QFN package at NSEB assembly site

**Pre Change:**

Using gold (Au) bond wire, 8200T and 8600 die attach and G770HCD and G700LTD mold compound material.

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

**Pre and Post Change Summary:**

	Pre Change		Post Change
<b>Assembly Site</b>	NSEB Assembly Site		NSEB Assembly Site
<b>Wire material</b>	Au Wire		CuPdAu Wire
<b>Die attach material</b>	8200T	8600	8600
<b>Molding compound material</b>	G770HCD	G700LTD	G700LTD
<b>Lead frame material</b>	EFTEC-64T		EFTEC-64T

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

October 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been

issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	April 2017						-->	October 2017				
	13	14	15	16	17	18		40	41	42	43	44
Initial PCN Issue Date					X							
Qual Report Availability								X				
Final PCN Issue Date								X				

**Method to Identify Change:**  
Traceability code

**Qualification Plan:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan

**Revision History:**  
**April 27, 2017:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN\\_KSRA-19GIRS482\\_Affected CPN.pdf](#)
  - [PCN\\_KSRA-19GIRS482\\_Qual Plan.pdf](#)
  - [PCN\\_KSRA-19GIRS482\\_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

<b>PCN_KSRA-19GIRS482</b>
<b>CATALOG_PART_NBR</b>
HA2223-I/ML
HA2223T-I/ML
PIC16F1713-E/ML
PIC16F1713-I/ML
PIC16F1713T-I/ML
PIC16F1716-E/ML
PIC16F1716-I/ML
PIC16F1716T-I/ML
PIC16F1718-E/ML
PIC16F1718-I/ML
PIC16F1718T-I/ML
PIC16F1782-E/ML
PIC16F1782-I/ML
PIC16F1782T-E/ML
PIC16F1782T-I/ML
PIC16F1783-E/ML
PIC16F1783-I/ML
PIC16F1783T-E/ML
PIC16F1783T-I/ML
PIC16F1786-E/ML
PIC16F1786-I/ML
PIC16F1786T-I/ML
PIC16F1788-E/ML
PIC16F1788-I/ML
PIC16F1788T-E/ML
PIC16F1788T-I/ML
PIC16F1826-E/ML
PIC16F1826-I/ML
PIC16F1826T-I/ML
PIC16F1827-E/ML
PIC16F1827-I/ML
PIC16F1827T-I/ML
PIC16F1847-E/ML
PIC16F1847-I/ML
PIC16F1847T-I/ML
PIC16F1933-E/ML
PIC16F1933-I/ML
PIC16F1933T-E/ML
PIC16F1933T-I/ML
PIC16F1936-E/ML
PIC16F1936-I/ML
PIC16F1936-I/MLC02
PIC16F1936T-I/ML

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<b>CATALOG_PART_NBR</b>
PIC16F1938-E/ML
PIC16F1938-I/ML
PIC16F1938-I/MLRA2
PIC16F1938T-I/ML
PIC16F1938T-I/MLRA2
PIC16F722A-E/ML
PIC16F722A-I/ML
PIC16F722AT-I/ML
PIC16F722-E/ML
PIC16F722-I/ML
PIC16F722T-I/ML
PIC16F723A-E/ML
PIC16F723A-I/ML
PIC16F723AT-I/ML
PIC16F723-E/ML
PIC16F723-I/ML
PIC16F723T-E/ML
PIC16F723T-I/ML
PIC16F726-E/ML
PIC16F726-I/ML
PIC16F726T-I/ML
PIC16LF1713-E/ML
PIC16LF1713-I/ML
PIC16LF1713T-I/ML
PIC16LF1716-E/ML
PIC16LF1716-I/ML
PIC16LF1716T-I/ML
PIC16LF1718-E/ML
PIC16LF1718-I/ML
PIC16LF1718T-I/ML
PIC16LF1782-E/ML
PIC16LF1782-I/ML
PIC16LF1782T-I/ML
PIC16LF1783-E/ML
PIC16LF1783-I/ML
PIC16LF1783T-I/ML
PIC16LF1786-E/ML
PIC16LF1786-I/ML
PIC16LF1786T-I/ML
PIC16LF1788-E/ML
PIC16LF1788-I/ML
PIC16LF1788T-I/ML
PIC16LF1826-E/ML

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<b>CATALOG_PART_NBR</b>
PIC16LF1826-I/ML
PIC16LF1826T-I/ML
PIC16LF1827-E/ML
PIC16LF1827-I/ML
PIC16LF1827T-I/ML
PIC16LF1847-E/ML
PIC16LF1847-I/ML
PIC16LF1847T-I/ML
PIC16LF1933-E/ML
PIC16LF1933-I/ML
PIC16LF1933T-I/ML
PIC16LF1936-E/ML
PIC16LF1936-I/ML
PIC16LF1936T-I/ML
PIC16LF1936T-I/ML020
PIC16LF1938-E/ML
PIC16LF1938-I/ML
PIC16LF1938-I/MLC01
PIC16LF1938T-E/ML
PIC16LF1938T-I/ML
PIC16LF1938T-I/MLC01
PIC16LF722A-E/ML
PIC16LF722A-I/ML
PIC16LF722AT-I/ML
PIC16LF722-E/ML
PIC16LF722-I/ML
PIC16LF722T-I/ML
PIC16LF723A-E/ML
PIC16LF723A-I/ML
PIC16LF723AT-I/ML
PIC16LF723-E/ML
PIC16LF723-I/ML
PIC16LF723T-I/ML
PIC16LF726-E/ML
PIC16LF726-I/ML
PIC16LF726T-I/ML
PIC18F23K20-E/ML
PIC18F23K20-I/ML
PIC18F23K20T-E/ML
PIC18F23K20T-I/ML
PIC18F23K22-E/ML
PIC18F23K22-I/ML
PIC18F23K22T-E/ML

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<b>CATALOG_PART_NBR</b>
PIC18F23K22T-I/ML
PIC18F24K20-E/ML
PIC18F24K20-I/ML
PIC18F24K20T-I/ML
PIC18F24K20T-I/ML028
PIC18F24K22-E/ML
PIC18F24K22-I/ML
PIC18F24K22T-E/ML
PIC18F24K22T-I/ML
PIC18F24K50-E/ML
PIC18F24K50-I/ML
PIC18F24K50T-I/ML
PIC18F25K20-E/ML
PIC18F25K20-I/ML
PIC18F25K20-I/MLC02
PIC18F25K20-I/MLC05
PIC18F25K20-I/MLC10
PIC18F25K20-I/MLLPR
PIC18F25K20T-E/ML
PIC18F25K20T-I/ML
PIC18F25K20T-I/MLC02
PIC18F25K20T-I/MLC10
PIC18F25K22-E/ML
PIC18F25K22-I/ML
PIC18F25K22T-E/ML
PIC18F25K22T-I/ML
PIC18F25K50-E/ML
PIC18F25K50-I/ML
PIC18F25K50T-E/ML
PIC18F25K50T-E/ML020
PIC18F25K50T-E/ML022
PIC18F25K50T-I/ML
PIC18F26K20-E/ML
PIC18F26K20-I/ML
PIC18F26K20-I/ML035
PIC18F26K20-I/MLC03
PIC18F26K20T-E/ML
PIC18F26K20T-I/ML
PIC18F26K20T-I/ML033
PIC18F26K20T-I/ML034
PIC18F26K20T-I/ML035
PIC18F26K20T-I/ML036
PIC18F26K20T-I/ML040

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<b>CATALOG_PART_NBR</b>
PIC18F26K20T-I/ML043
PIC18F26K20T-I/MLC03
PIC18F26K22-E/ML
PIC18F26K22-I/ML
PIC18F26K22T-E/ML
PIC18F26K22T-I/ML
PIC18F26K22T-I/ML024
PIC18LF23K22-E/ML
PIC18LF23K22-I/ML
PIC18LF23K22T-I/ML
PIC18LF23K22T-I/ML020
PIC18LF23K22T-I/ML021
PIC18LF24K22-E/ML
PIC18LF24K22-I/ML
PIC18LF24K22T-I/ML
PIC18LF24K50-E/ML
PIC18LF24K50-I/ML
PIC18LF24K50T-I/ML
PIC18LF25K22-E/ML
PIC18LF25K22-I/ML
PIC18LF25K22T-I/ML
PIC18LF25K50-E/ML
PIC18LF25K50-I/ML
PIC18LF25K50T-I/ML
PIC18LF26K22-E/ML
PIC18LF26K22-I/ML
PIC18LF26K22-I/MLC04
PIC18LF26K22-I/MLC05
PIC18LF26K22-I/MLC06
PIC18LF26K22T-E/ML
PIC18LF26K22T-I/ML
PIC18LF26K22T-I/ML024
PIC18LF26K22T-I/MLC04
PIC18LF26K22T-I/MLC05
PIC18LF26K22T-I/MLC06
PIC24F08KA102-E/ML
PIC24F08KA102-I/ML
PIC24F08KL302-E/ML
PIC24F08KL302-I/ML
PIC24F08KL302-I/MQ
PIC24F08KL302T-I/MQ
PIC24F08KL402-I/ML
PIC24F08KL402-I/MQ

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<b>CATALOG_PART_NBR</b>
PIC24F08KM202-I/ML
PIC24F16KA102-E/ML
PIC24F16KA102-I/ML
PIC24F16KA102T-I/ML
PIC24F16KA302-I/ML
PIC24F16KA302T-I/ML
PIC24F16KL402-E/ML
PIC24F16KL402-E/MQ
PIC24F16KL402-I/ML
PIC24F16KL402-I/MQ
PIC24F16KL402T-I/ML
PIC24F16KL402T-I/MQ
PIC24F16KM102-I/ML
PIC24F16KM202-E/ML
PIC24F16KM202-I/ML
PIC24F32KA302-E/ML
PIC24F32KA302-I/ML
PIC24F32KA302T-E/ML
PIC24F32KA302T-I/ML
PIC24FV08KM202-I/ML
PIC24FV16KA302-I/ML
PIC24FV16KA302T-I/ML
PIC24FV16KM102-I/ML
PIC24FV16KM202-E/ML
PIC24FV16KM202-I/ML
PIC24FV16KM202T-I/ML
PIC24FV32KA302-I/ML
PIC24FV32KA302T-I/ML